

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00111	0.66	0.066
	Doped silicon	Silicon (Si)	7440-21-3	0.1669	99.34	9.934
		Subtotal		0.16801	100	10
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.36962	100.0	22
		Subtotal		0.36962	100	22
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02011	0.03	1.197
	Copper alloy	Iron (Fe)	7439-89-6	0.06704	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.94914	99.87	3,984.813
		Subtotal		67.03629	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.08913	6.5	124.345
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.14247	16.0	306.08
	Filler	Silica fused	60676-86-0	22.81972	71.0	1,358.23
	Flame retardant	Metal hydroxide		2.08913	6.5	124.345
		Subtotal		32.14045	100	NaN
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.0084	5.0	0.5
	Lead alloy	Silver (Ag)	7440-22-4	0.0042	2.5	0.25
	Lead alloy	Lead (Pb)	7439-92-1	0.15541	92.5	9.25
		Subtotal		0.16801	100	10
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11761	100.0	7
		Subtotal		0.11761	100	7
		Total		99.99999	100	NaN

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